AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions of claims in the application:

Listing of Claims:

- 1. (original) An adhesive material satisfying the following requirements (a) and (b):
 - (a) the adhesive material comprises at least one kind of an olefinic polymer; and
- (b) by measurement according to a differential scanning calorimetry test, the melting temperature Tm is in the range of 80°C to 180°C and the heat of fusion ΔH is at least 1 J/g.
- 2. (original) The adhesive material according to claim 1, further satisfying the following requirement (c):
- (c) the storage elastic modulus G' at a temperature range of 20°C to 80°C is in the range of 0.1 to 50 MPa while the loss coefficient tan δ at a temperature range of 20°C to 80°C is at least 0.05.
- 3. (original) The adhesive material according to claim 2, further satisfying the following requirement (d):
 - (d) the peak of the loss coefficient tan δ is in the range of -20°C to +10°C.
- 4. (original) The adhesive material according to claim 1, wherein the olefinic polymer contains a propylene/olefin copolymer having tacticity (hereinafter referred to as PX) obtained by polymerizing 90 to 60 mole % of the propylene component with 10 to 40 mole % of at least one olefin component selected from ethylene and olefins having 4 to 12 carbon atoms.

- 5. (original) The adhesive material according to claim 4, further comprising an additional olefinic polymer (hereinafter referred to as PY), wherein the additional olefinic polymer (PY) is a polypropylene having the same tacticity as the propylene/olefin copolymer having tacticity (PX), and wherein the polymer ratio {(PX)/(PY)} is in the range of a weight ratio of 99/1 to 40/60.
- 6. (original) An adhesive film with an adhesive material layer laminated on at least one surface of a base material layer, wherein the adhesive material layer satisfies the following requirements (a) and (b):
- (a) the adhesive material layer comprises at least one kind of an olefinic polymer; and
- (b) by measurement according to a differential scanning calorimetry test, the melting temperature Tm is in the range of 80°C to 180°C and the heat of fusion ΔH is at least 1 J/g.
- 7. (original) The adhesive film according to claim 6, wherein the adhesive material layer further satisfies the following requirement (c):
- (c) the storage elastic modulus G' at a temperature range of 20°C to 80°C is in the range of 0.1 to 50 MPa while the loss coefficient tan δ at a temperature range of 20°C to 80°C is at least 0.05.
- 8. (currently amended) The adhesive film according to claim [[6]] 7, wherein the adhesive material layer further satisfies the following requirement (d):
 - (d) the peak of the loss coefficient tan δ is in the range of -20°C to +10°C.

- 9. (original) The adhesive film according to claim 6, wherein the olefinic polymer contains a propylene/olefin copolymer having tacticity (PX) obtained by polymerizing 90 to 60 mole % of the propylene component with 10 to 40 mole % of at least one olefin component selected from ethylene and olefins having 4 to 12 carbon atoms.
- 10. (original) The adhesive film according to claim 9, further comprising an additional olefinic polymer (PY), wherein the additional olefinic polymer (PY) is a polypropylene having the same tacticity as the propylene/olefin copolymer having tacticity (PX), and wherein the polymer ratio {(PX)/(PY)} is in the range of a weight ratio of 99/1 to 40/60.
- 11. (original) The adhesive film according to claim 6, wherein the total content ratio of each ion extracted by pure water is not more than 1 ppm.
- 12. (original) The adhesive film according to claim 6, wherein the base material layer and the adhesive material layer are formed into a film by a co-extrusion method.
- 13. (original) A method of using the adhesive film as described in claim 6, which comprises using the adhesive film for surface protection in combination of at least one application selected from treatment with a chemical solution, heating treatment, grinding processing, polishing processing, cutting processing and transport storage.